

RoHS

COMPLIANT

N-Channel 150-V (D-S) 175 °C MOSFET

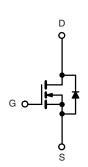
PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)		
150	0.030 at V _{GS} = 10 V	50		
150	0.033 at V _{GS} = 6 V	45		

FEATURES

- TrenchFET[®] Power MOSFETs
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_{C} = 25 \text{ °C}$, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	150		
Gate-Source Voltage	V _{GS}	± 20	V		
Continuous Drain Current (T ₁ = 175 °C)	T _C = 25 °C	1-	50		
Continuous Drain Current $(1) = 175$ C)	T _C = 125 °C	I _D	35		
Pulsed Drain Current	I _{DM}	150	A		
Avalanche Current	I _{AR}	50			
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	80	mJ	
	T _C = 25 °C	P	166 ^b	w	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75		
Operating Junction and Storage Temperature F	lange	T _J , T _{stg}	- 55 to 175	°C	

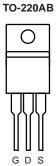
THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	R _{thJC}	0.9	- °C/W		

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).



Top View



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 V, I_{D} = 250 \mu A$	150			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 120 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 120 V, V_{GS} = 0 V, T_{J} = 125 °C			50		
		$V_{DS} = 120 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	80			Α	
		V _{GS} = 10 V, I _D = 15 A		0.030			
	P	$V_{GS} = 6 V, I_D = 10 A$		0.033		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 15 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$		0.076			
		V _{GS} = 10 V, I _D = 15 A, T _J = 175 °C		0.100			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	10			S	
Dynamic ^b	4		<u> </u>	+	L 1		
Input Capacitance	C _{iss}			2500		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		290			
Reverse Transfer Capacitance	C _{rss}			190			
Gate Resistance	Rg			2		Ω	
Total Gate Charge ^c	Qg			38	60	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$		13			
Gate-Drain Charge ^c	Q _{gd}			13			
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	V_{DD} = 75 V, R _L = 1.80 Ω		130	200		
Turn-Off Delay Time ^c	t _{d(off)}	$\text{I}_{\text{D}}\cong$ 40 A, V_{GEN} = 10 V, R_{g} = 2.5 Ω		30	45	- ns	
Fall Time ^c	t _f			90	140		
Source-Drain Diode Ratings and Cha	aracteristics 7	$\Gamma_{\rm C} = 25 \ {}^{\circ}{\rm C}^{\rm b}$			1		
Continuous Current	ا _S				40		
Pulsed Current	I _{SM}			1	80	A	
Forward Voltage ^a	V _{SD}	I _F = 40 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			100	150	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 40 A, dl/dt = 100 A/μs		5	8	Α	
Reverse Recovery Charge	Q _{rr}	1		0.25	0.6	μC	

Notes:

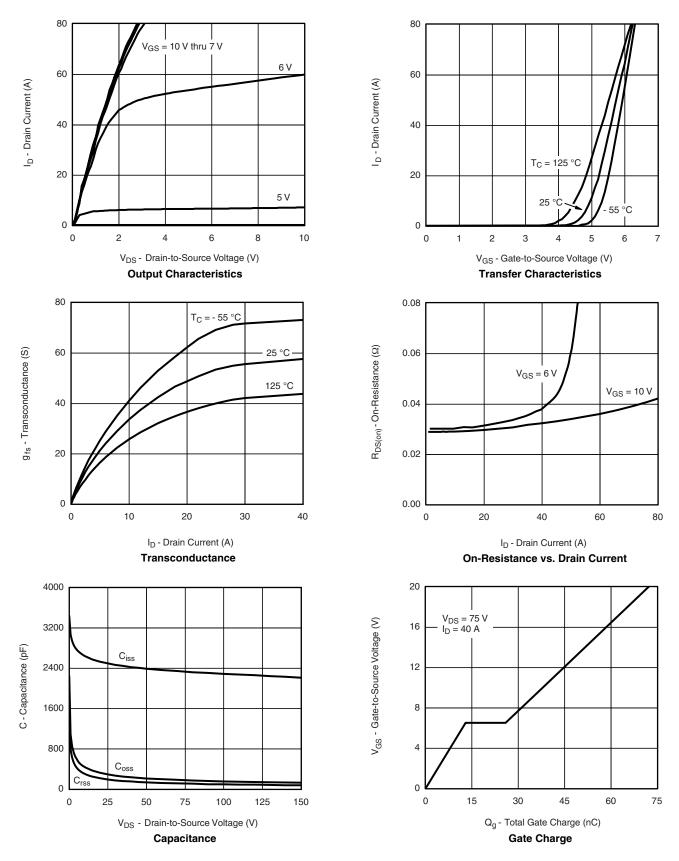
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

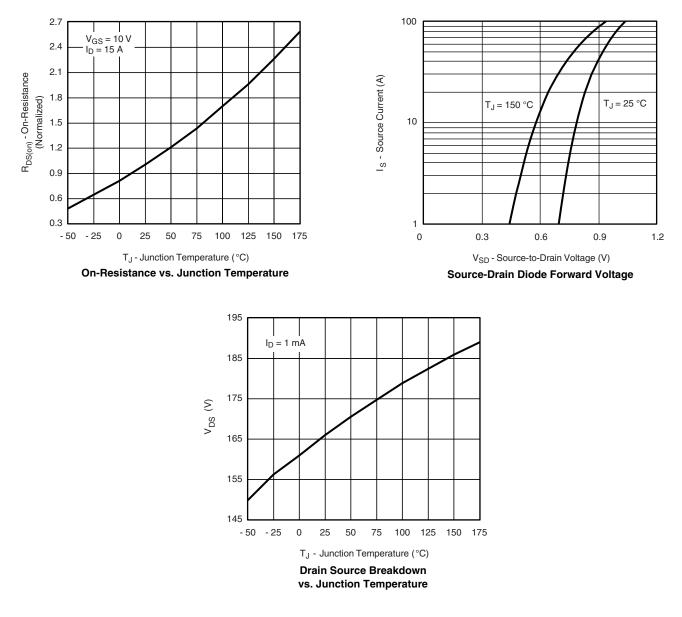


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





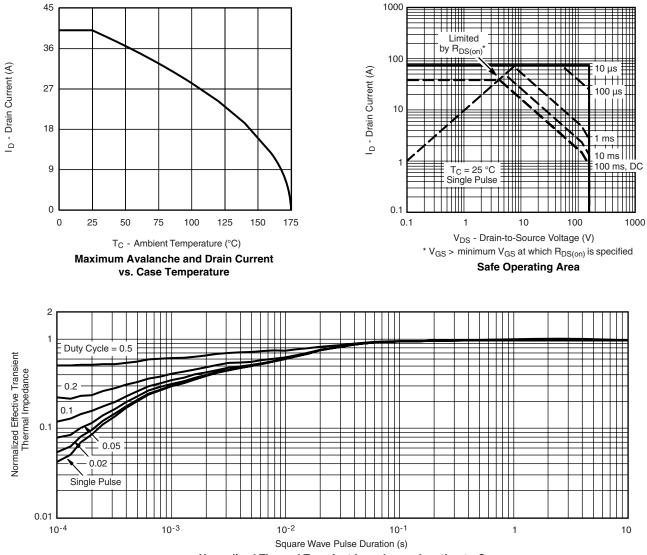
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



IRFB41N15DPBF



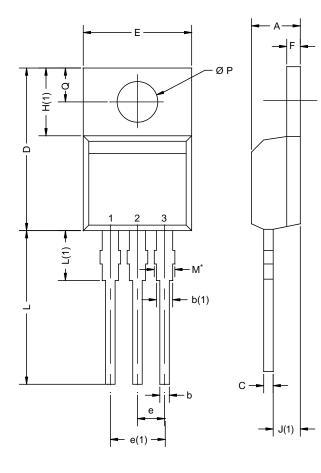
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
E	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
	ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471				

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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